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# Linear Voltage Regulator, Multiple-Output, System Power Supply IC, for Automotive Infotainment System

#### Overview

The LV5680NPVC is a multi-power supply system IC that provides four regulator outputs and two high side switches as well as a number of protection functions including overcurrent protection, overvoltage protection and overheat protection. It is an optimal power supply IC for car audio and car entertainment systems and similar products.

#### **Features**

• Four regulator output systems

For microcontroller: 5.0V output voltage, 200mA maximum output current

For CD drive: 8.0V output voltage, 1300mA maximum output current For illumination: 8 to 12V output voltage (output can be set with external resistors), 300mA maximum output current

For audio systems: 8 to 9V output voltage (output voltage can be set with external resistors), 300mA maximum output current

• Two V<sub>CC</sub>-linked high side switch systems

EXT: 350mA maximum output current, 0.5V voltage difference between input and output.

ANT: 300mA maximum output current, 0.5V voltage difference between input and output.

• Two V<sub>DD</sub> 5V-linked high side switch systems

SW5V: 200mA maximum output current, 0.2V voltage difference between input and output.

ACC (accessory voltage detection output): 100mA maximum output current, 0.2V voltage difference between input and output.

- Overcurrent protection function
- Overvoltage protection function, typ 21V (excluding V<sub>DD</sub> 5V output)
- Overheat protection function, typ 175°C
- · On-chip accessory voltage detection circuit
- P-channel LDMOS used for power output block

(Warning) The protector functions only improve the IC's tolerance and they do not guarantee the safety of the IC if used under the conditions out of safety range or ratings. Use of the IC such as use under over current protection range or thermal shutdown state may degrade the IC's reliability and eventually damage the IC.

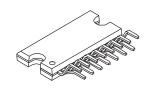
### **Typical Applications**

• Automotive infotainment



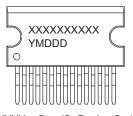
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HZIP15J

# GENERIC MARKING DIAGRAM



XXXXX = Specific Device Code Y = Year M = Month DDD = Additional Traceability Data

#### **ORDERING INFORMATION**

Ordering Code: LV5680NPVC-XH

Package HZIP15J (Pb-Free / Halogen Free)

Shipping (Qty / packing) 20 / Fan-Fold

## **Specifications**

### Absolute Maximum Ratings at Ta = 25°C (Note 1)

Parameter	Conditions	Conditions		Ratings	Unit
Supply voltage	V <sub>CC</sub> max			36	V
Peak supply voltage	V <sub>CC</sub> peak	See below for the waveform ap	plied.	50	V
Allowable Power dissipation	Pd max	Independent IC	Ta ≤ 25°C	1.5	W
		Al heat sink (Note 2)		5.6	W
		With an infinity heat sink		32.5	W
Junction temperature	Tj max			150	°C
Operating ambient temperature	Topr			-40 to +85	°C
Storage temperature	Tstg			-55 to +150	°C

<sup>1.</sup> Stresses exceeding those listed in the Maximum Rating table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

### Recommended Operating Ranges at Ta = 25°C (Note 3)

Parameter	Conditions	Ratings	Unit
Operating supply voltage 1	V <sub>DD</sub> output, SW output, ACC output	7.5 to 16	V
Operating supply voltage 2	ILM output at 10V	12 to 16	V
	ILM output at 8V	10 to 16	V
Operating supply voltage 3	Audio output at 9V	10 to 16	V
Operating supply voltage 4	CD output (CD output current = 1.3A)	10.5 to 16	V
	CD output (CD output current ≤ 1A)	10 to 16	V

<sup>3.</sup> Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

### Electrical Characteristics at V<sub>CC</sub> = 14.4V, Ta = 25°C (Note 4,10)

Denometer	Courselle al	Conditions		Ratings		Unit
Parameter	Symbol	Conditions	min	typ	max	Unit
Current drain	Icc	$V_{DD}$ no load, CTRL1/2 = $\lceil L/L \rfloor$ , ACC = 0V		400	800	μΑ
CTRL1 Input	CTRL1 Input					
Low input voltage	V <sub>IL</sub> 1		0		0.5	V
M1 input voltage	V <sub>IM1</sub> 1		0.8	1.1	1.4	V
M2 input voltage	V <sub>IM2</sub> 1		1.9	2.2	2.5	V
High input voltage	V <sub>IH</sub> 1		2.9	3.3	5.5	V
Input impedance	R <sub>IH</sub> 1		350	500	650	kΩ
CTRL2 Input						
Low input voltage	V <sub>IL</sub> 2		0		0.5	V
M input voltage	V <sub>IM</sub> 2		1.1	1.65	2.1	V
High input voltage	V <sub>IH</sub> 2		2.5	3.3	5.5	V
Input impedance	R <sub>IH</sub> 2		350	500	650	kΩ
V <sub>DD</sub> 5V Output (Note 5)		The V <sub>DD</sub> 5V output sup	plies the outp	ut currents o	f SW 5V and	ACC 5V.
Output voltage 1	V <sub>O</sub> 1	I <sub>O</sub> 1 = 200mA, I <sub>O</sub> 7, I <sub>O</sub> 8 = 0A	4.75	5.0	5.25	V
Output voltage 2	V <sub>O</sub> 1'	I <sub>O</sub> 1 = 200mA, I <sub>O</sub> 7 = 200mA, I <sub>O</sub> 8 = 100mA	4.75	5.0	5.25	V
Output total current	Ito1	$V_{O}1 \ge 4.75V$ , Ito1 = $I_{O}1+I_{O}7+I_{O}8$	500			mA
Line regulation	ΔV <sub>OLN</sub> 1	$7.5V < V_{CC} < 16V, I_{O}1 = 200mA \text{ (Note 6)}$		30	90	mV
Load regulation	ΔV <sub>OLD</sub> 1	1mA < I <sub>O</sub> 1 < 200mA (Note 6)		70	150	mV
Dropout voltage 1	V <sub>DROP</sub> 1	I <sub>O</sub> 1 = 200mA (Note 6)		1.0	1.5	V
Dropout voltage 2	V <sub>DROP</sub> 1'	I <sub>O</sub> 1 = 100mA (Note 6)		0.7	1.05	V
Dropout voltage 3	V <sub>DROP</sub> 1"	I <sub>O</sub> 1+I <sub>O</sub> 7+I <sub>O</sub> 8 = 500mA		2.5	3.75	V
Ripple rejection	R <sub>REJ</sub> 1	f = 120Hz, I <sub>O</sub> 1 = 200mA (Note 6)	40	50		dB

Continued on next page.

<sup>2.</sup> When the Aluminum heat sink (50mm  $\times$  50mm  $\times$  1.5mm) is used

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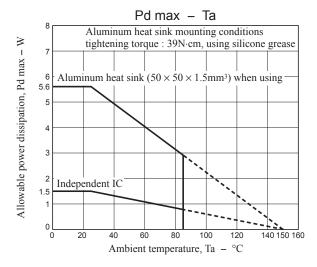
Parameter	Symbol	Conditions		Ratings		Unit
	Cymbol	Conditions	min	typ	max	O mic
CD Output ; CTRL2 = [H]		1	Γ Ι		1	
Output voltage	V <sub>O</sub> 2	I <sub>O</sub> 2 = 1000mA	7.6	8.0	8.4	V
Output current	I <sub>O</sub> 2	V <sub>O</sub> 2 ≥ 7.6V	1300			mA
Line regulation	∆V <sub>OLN</sub> 2	10.5V < V <sub>CC</sub> < 16V, I <sub>O</sub> 2 = 1000mA		50	100	mV
Load regulation	∆V <sub>OLD</sub> 2	10mA < I <sub>O</sub> 2 < 1000mA		100	200	mV
Dropout voltage 1	V <sub>DROP</sub> 2	I <sub>O</sub> 2 = 1000mA		1.0	1.5	V
Dropout voltage 2	V <sub>DROP</sub> 2'	I <sub>O</sub> 2 = 500mA		0.5	0.75	V
Ripple rejection	R <sub>REJ</sub> 2	f = 120Hz, I <sub>O</sub> 2 = 1000mA	40	50		dB
AUDIO (8-9V) Output ; CTRL2 =	[м]					
AUDIO_F pin voltage	V <sub>I</sub> 3		1.222	1.260	1.298	V
AUDIO_F pin inflow current	I <sub>IN</sub> 3		-1		1	μΑ
AUDIO output voltage 1	V <sub>O</sub> 3	$I_O$ 3 = 200mA, R2 = 30kΩ, R3 = 5.6kΩ (Note 7)	7.65	8.0	8.35	V
AUDIO output voltage 2	V <sub>O</sub> 3'	$I_{O}3 = 200 \text{mA}, R2 = 27 \text{k}\Omega, R3 = 4.7 \text{k}\Omega \text{ (Note 7)}$	8.13	8.5	8.87	V
AUDIO output voltage 3	V <sub>O</sub> 3"	$I_{O}3 = 200$ mA, R2 = 24k $\Omega$ , R3 = 3.9k $\Omega$ (Note 7)	8.6	9.0	9.4	V
AUDIO output current	I <sub>O</sub> 3		300			mA
Line regulation	ΔV <sub>OLN</sub> 3	10V < V <sub>CC</sub> < 16V, I <sub>O</sub> 3 = 200mA		30	90	mV
Load regulation	ΔV <sub>OLD</sub> 3	1mA < I <sub>O</sub> 3 < 200mA		70	150	mV
Dropout voltage 1	V <sub>DROP</sub> 3	I <sub>O</sub> 3 = 200mA		0.3	0.45	V
Dropout voltage 2	V <sub>DROP</sub> 3'	I <sub>O</sub> 3 = 100mA		0.15	0.23	V
Ripple rejection	R <sub>REJ</sub> 3	f = 120Hz, I <sub>O</sub> 3 = 200mA	40	50		dB
ILM (8-12V) Output ; CTRL1 =		1		<u> </u>		
ILM_F pin voltage	V <sub>I</sub> 4		1.222	1.260	1.298	V
ILM output voltage 1	V <sub>O</sub> 4	I <sub>O</sub> 4 = 200mA	11.4	12.0	12.6	V
ILM output voltage 2	V <sub>O</sub> 4'	$I_{\Omega}4 = 200 \text{mA}, R1 = 270 \text{k}\Omega \text{ (Note 8)}$	8.5	10.0	11.5	V
ILM output voltage 3	V <sub>O</sub> 4"	$I_{\Omega}4 = 200 \text{mA}, R1 = 100 \text{k}\Omega \text{ (Note 8)}$	6.8	8.0	9.2	V
ILM output current	104	R1 = 270kΩ	300		-	mA
Line regulation	ΔV <sub>OLN</sub> 4	$12V < V_{CC} < 16V$ , $I_{O}4 = 200$ mA, R1 = $270$ k $\Omega$		30	90	mV
Load regulation	ΔV <sub>OLD</sub> 4	1mA < I <sub>O</sub> 4 < 200mA		70	150	mV
Dropout voltage 1	V <sub>DROP</sub> 4	I <sub>O</sub> 4 = 200mA		0.7	1.05	V
Dropout voltage 2	V <sub>DROP</sub> 4'	I <sub>O</sub> 4 = 100mA		0.35	0.53	
Ripple rejection		f = 120Hz, I <sub>O</sub> 4 = 200mA	40	50	0.00	dB
Remoto (EXT) ; CTRL1 = M2	R <sub>REJ</sub> 4	1 - 120112, 104 - 200111A	40	30		ub
Output voltage	V <sub>O</sub> 5	I <sub>O</sub> 5 = 350mA	V <sub>CC</sub> -1.0	V <sub>CC</sub> -0.5		V
Output current	I <sub>O</sub> 5	V <sub>O</sub> 5 ≥ V <sub>CC</sub> -1.0	350	V()() 0.0		mA
ANT remoto ; CTRL1 = [H]	103	V00 ≥ VCC-1.0	330			ША
Output voltage	V <sub>O</sub> 6	I <sub>O</sub> 6 = 300mA	V <sub>CC</sub> -1.0	V <sub>CC</sub> -0.5		V
Output current	I <sub>O</sub> 6	V <sub>O</sub> 6 ≥ V <sub>CC</sub> -1.0	300	VCC-0.3		mA
SW 5V Output ; CTRL2 = M	100	V00 ≥ VCC-1.0	300			IIIA
Output voltage 1	V <sub>O</sub> 7	I <sub>O</sub> 7 = 1mA, I <sub>O</sub> 1, I <sub>O</sub> 8 = 0A (Note 9)	V <sub>O</sub> 1-0.25	V <sub>O</sub> 1		V
Output voltage 2	, ,		V <sub>O</sub> 1-0.25			
	V <sub>O</sub> 7'	I <sub>O</sub> 7 = 200mA, I <sub>O</sub> 1, I <sub>O</sub> 8 = 0A (Note 9)		V <sub>O</sub> 1-0.2		
Output current  ACC Detection ; ACC Integration	I <sub>O</sub> 7	V <sub>O</sub> 7 ≥ 4.55	200			mA
		T	0.0	201	2.0	١,,
ACC detection voltage	V <sub>TH</sub> 8		2.8	3.0	3.2	V
Hysteresis width	V <sub>HIS</sub> 8	(D. II. da	0.2	0.3	0.4	V
Input impedance	ZI8	(Pull-down resistance internal)	42	60	78	kΩ
ACC output voltage 1	V <sub>O</sub> 8	I <sub>O</sub> 8 = 0.5mA, I <sub>O</sub> 1, I <sub>O</sub> 7 = 0A (Note 9)	V <sub>O</sub> 1-0.25	V <sub>O</sub> 1		V
ACC output voltage 2	V <sub>0</sub> 8'	I <sub>O</sub> 8 = 100mA, I <sub>O</sub> 1, I <sub>O</sub> 7 = 0A (Note 9)	V <sub>O</sub> 1-0.45	V <sub>O</sub> 1-0.2		V
ACC output voltage	I <sub>O</sub> 8	V <sub>O</sub> 8 ≥ 4.55	100			mA

<sup>4.</sup> Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

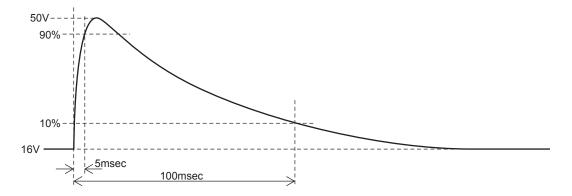
- 5. The V<sub>DD</sub> 5V output also supplies the output currents of SW 5V and ACC 5V. Therefore, the current supply capability of the V<sub>DD</sub> 5V output and its other electrical characteristics are affected by the output statuses of SW 5V and ACC 5V. 6. SW 5V and ACC 5V are not subject to a load.
- 7. When a component with a resistance accuracy of  $\pm 1\%$  is used <Reference> When a component with a resistance accuracy of  $\pm 0.5\%$  is used,  $V_O3$ " is  $8.67V \le 9.0V \le 9.33V$
- 8. When a component with a resistance accuracy of  $\pm 1\%$  is used
- The absolute accuracy of the internal resistance is ±15%

  9. Since the SW 5V and ACC 5V are output from VDD 5V through the SW, the voltage drops by an amount equivalent to the ON resistance of the SW.
- 10. The entire specification has been defined based on the tests performed under the conditions where Tj and Ta (=25°C) are almost equal. There tests were performed with pulse load to minimize the increase of junction temperature (Tj).

### • Allowable power dissipation derating curve



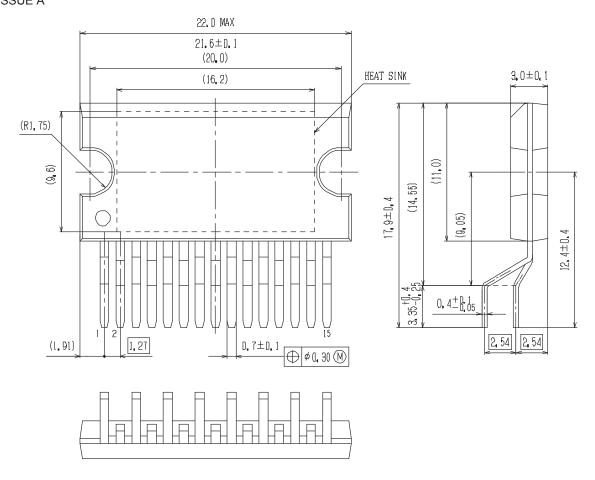
### • Waveform applied during surge test



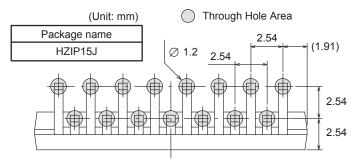
# **Package Dimensions**

unit:mm

**HZIP15J** CASE 945AC ISSUE A



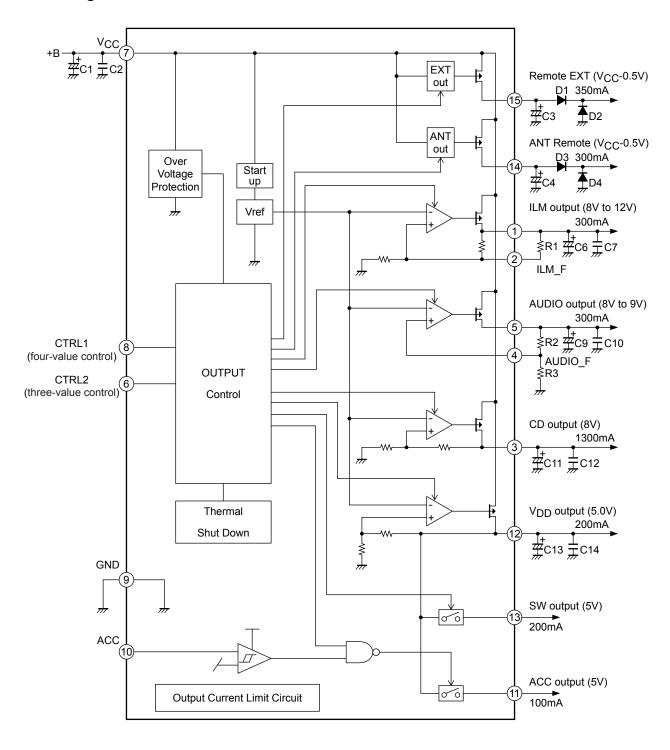
#### **SOLDERING FOOTPRINT\***



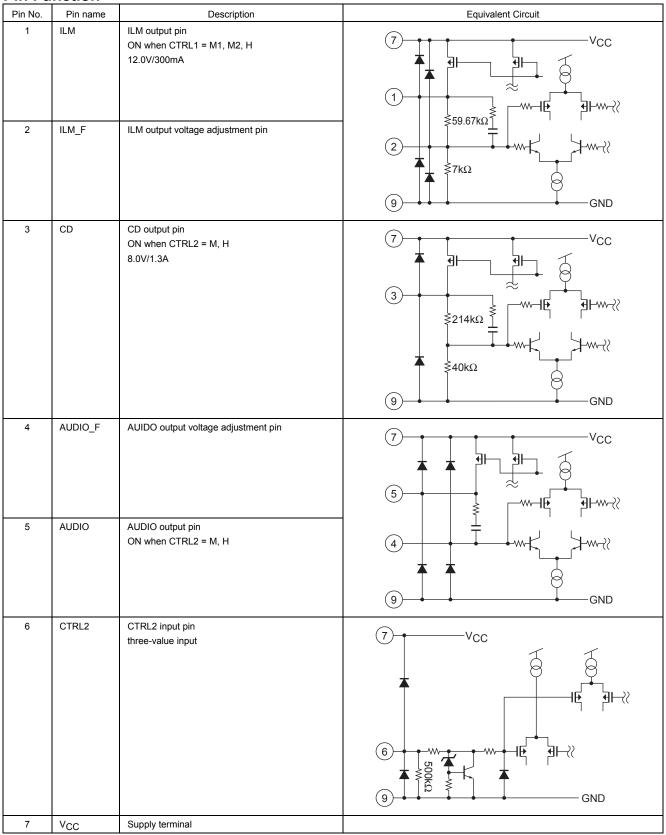
NOTE: The measurements are not to guarantee but for reference only.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **Block Diagram**



### **Pin Function**



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Pin No.	Pin name	Description	Equivalent Circuit
8	CTRL1	CTRL1 input pin four-value input	8 9 C3/00067 C3/0067 C
9	GND	GND pin	
10	ACC	Accessory input	7 Vcc Vcc Vcc 45kΩ Fl-w-? GND
11	ACC5V	Accessory detection output ON when ACC > 3V	7 VCC
12	V <sub>DD</sub> 5V	V <sub>DD</sub> 5V output pin 5.0V/200mA SW5V output pin	12 11 13 13 12 125kΩ
		ON when CTRL2 = M, H	13 \$125kΩ \$125kΩ GND
14	ANT	ANT output pin ON when CTRL1 = H V <sub>CC</sub> -0.5V/300mA	7 VCC VCC VCC VCC VCC VCC VCC VCC VCC VC

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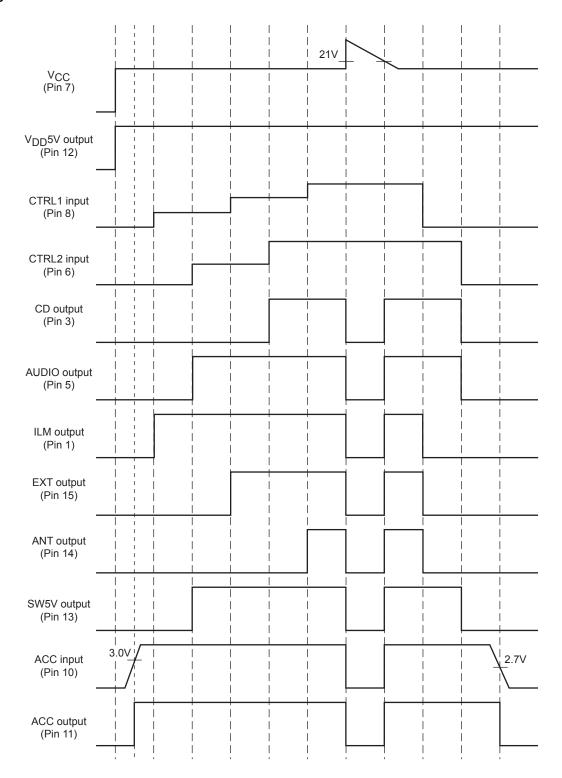
Pin No.	Pin name	Description	Equivalent Circuit
15	EXT	EXT output pin ON when CTRL1 = M2, H V <sub>CC</sub> -0.5V/350mA	7 VCC

**CTRL Pin Output Truth Table** 

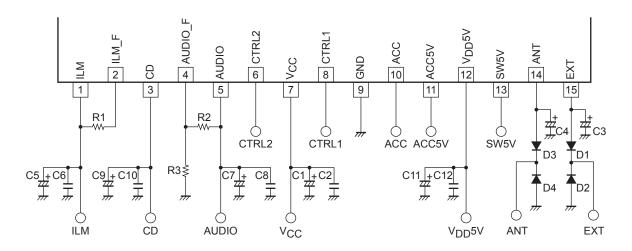
CTRL1	ANT	EXT	ILM
L	OFF	OFF	OFF
M1	OFF	OFF	ON
M2	OFF	ON	ON
Н	ON	ON	ON

CTRL2	CD	AUDIO	SW5
L	OFF	OFF	OFF
М	OFF	ON	ON
Н	ON	ON	ON

### **Timing Chart**



# **Recommended Operation Circuit**



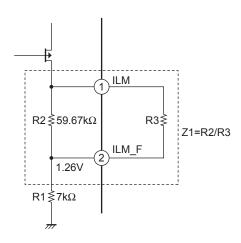
### Peripheral parts list

Name of part	Description	Recommended value	Remarks
C1	Power supply bypass capacitor	100μF or more	These capacitors must be placed near the
C2	Oscillation prevention capacitor	0.22μF or more	V <sub>CC</sub> and GND pins.
C3	EXT output stabilization capacitor	2.2μF or more	
C4	ANT output stabilization capacitor	2.2μF or more	
C5, C7, C9, C11	Output stabilization capacitor	4.7μF or more	Electrolytic capacitor *
C6, C8, C10, C12	Output stabilization capacitor	0.22μF or more	Ceramic capacitor *
R1	Resistor for ILM voltage adjustment	ILM output voltage R1:without = 12.0V :270kΩ = 10.0V :100kΩ = 8.0V	A resistor with resistance accuracy as low as less than $\pm 1\%$ must be used.
R2, R3	Resistor for AUDIO voltage setting	AUDIO output voltage R2/R3:30 $\kappa\Omega$ /5.6 $\kappa\Omega$ = 8.0V :27 $\kappa\Omega$ /4.7 $\kappa\Omega$ = 8.5V :24 $\kappa\Omega$ /3.9 $\kappa\Omega$ = 9.0V	A resistor with resistance accuracy as low as less than $\pm 1\%$ must be used.
D1, D2, D3, D4	Diode for internal device breakdown protection		

<sup>\*:</sup> In order to stabilize the regulator outputs, it is recommended that the electrolytic capacitor and ceramic capacitor be connected in parallel.

Furthermore, the values listed above do not guarantee stabilization during the overcurrent protection operations of the regulator, so oscillation may occur during an overcurrent protection operation.

### • ILM output voltage setting method



The ILM\_F voltage is determined by the internal band gap voltage of the IC (typ = 1.26V).

Formula for ILM voltage calculation

$$Z_1 = R_2 / / R_3 = \frac{R_2 \cdot R_3}{R_2 + R_3}$$

$$ILM = \frac{1.26[V]}{R_1} \times Z_1 + 1.26[V]$$

$$Z_1 = \frac{(ILM - 1.26) \cdot R_1}{1.26}$$
  $R_3 = \frac{R_2 \cdot Z_1}{R_2 - Z_1}$ 

Example : ILM = 9V setting method

$$Z_1 = \frac{(9V - 1.26V) \cdot 7k\Omega}{1.26V} \cong 43k\Omega$$

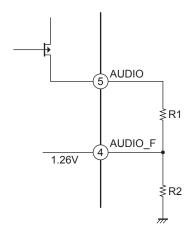
$$R_3 = \frac{59.67k\Omega \cdot 43k\Omega}{59.67k\Omega - 43k\Omega} \cong 153.9k\Omega \rightarrow \boxed{150k\Omega}$$

When R3 = 150k, the ILM output voltage will be as follows:

$$Z_1' = \frac{59.67k\Omega \cdot 150k\Omega}{59.67k\Omega + 150k\Omega} \approx 42.69k\Omega$$

$$ILM = \frac{1.26V}{7k\Omega} \times 42.69k\Omega + 1.26V \cong 8.94V$$

### • AUDIO output voltage setting method



The AUDIO\_F voltage is determined by the internal band gap voltage of the IC (typ = 1.26V).

Formula for AUDIO voltage calculation

$$AUDIO = \frac{1.26[V]}{R_2} \times R_1 + 1.26[V]$$

$$\frac{R_1}{R_2} = \frac{\left(AUDIO - 1.26\right)}{1.26}$$

The circuit must be designed in such a way that the R1:R2 ratio satisfies the formula given above for the AUDIO voltage that has been set.

Example : AUDIO = 8.5V setting method

$$\frac{R_1}{R_2} = \frac{\left(8.5 - 1.26\right)}{1.26} \cong 5.75$$

$$\frac{R_1}{R_2} = \frac{27k\Omega}{4.7k\Omega} \cong 5.74$$

$$AUDIO = 1.26V \times 5.74 + 1.26V \cong \boxed{8.49V}$$

Note: In the above, the typical values are given in all instances for the values used and, as such, they will vary due to the effects of production-related variations of the IC and external resistors.

• CTRL1 Application Circuit Example

(1) 3.3V input:  $R1 = 4.7k\Omega$ ,  $R2 = 10k\Omega$ 

Α	В	CTRL1
0V	0V	0V
0V	3.3V	1.05V
3.3V	0V	2.23V
3.3V	3.3V	3.20V

• CTRL2 Application Circuit Example

(1) 3.3V input:  $R3 = R4 = 4.7k\Omega$ 

Α	В	CTRL2
0V	0V	0V
0V	3.3V	1.61V
3.3V	0V	1.61V
3.3V	3.3V	3.29V

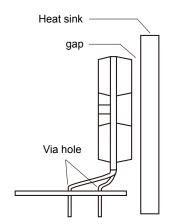
#### HZIP15J Heat sink attachment

Heat sinks are used to lower the semiconductor device junction temperature by leading the head generated by the device to the outer environment and dissipating that heat.

a. Unless otherwise specified, for power ICs with tabs and power ICs with attached heat sinks, solder must not be applied to the heat sink or tabs.

#### b. Heat sink attachment

- · Use flat-head screws to attach heat sinks.
- · Use also washer to protect the package.
- · Use tightening torques in the ranges 39-59Ncm(4-6kgcm).
- · If tapping screws are used, do not use screws with a diameter larger than the holes in the semiconductor device itself.
- Do not make gap, dust, or other contaminants to get between the semiconductor device and the tab or heat sink.
- · Take care a position of via hole.
- Do not allow dirt, dust, or other contaminants to get between the semiconductor device and the tab or heat sink.
- · Verify that there are no press burrs or screw-hole burrs on the heat sink.
- · Warping in heat sinks and printed circuit boards must be no more than 0.05 mm between screw holes, for either concave or convex warping.
- · Twisting must be limited to under 0.05 mm.
- · Heat sink and semiconductor device are mounted in parallel. Take care of electric or compressed air drivers
- The speed of these torque wrenches should never exceed 700 rpm, and should typically be about 400 rpm.



Countersunk head

Binding head machine screw

#### c.Silicone grease

- · Spread the silicone grease evenly when mounting heat sinks.
- · Our company recommends YG-6260 (Momentive Performance Materials Japan LLC)

### d. Mount

- · First mount the heat sink on the semiconductor device, and then mount that assembly on the printed circuit board.
- · When attaching a heat sink after mounting a semiconductor device into the printed circuit board, when tightening up a heat sink with the screw, the mechanical stress which is impossible to the semiconductor device and the pin doesn't hang.
- e. When mounting the semiconductor device to the heat sink using jigs, etc.,
  - Take care not to allow the device to ride onto the jig or positioning dowel.
  - Design the jig so that no unreasonable mechanical stress is not applied to the semiconductor device.

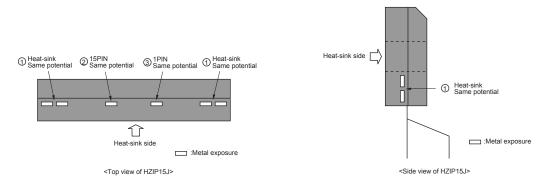
#### f. Heat sink screw holes

- Be sure that chamfering and shear drop of heat sinks must not be larger than the diameter of screw head used.
- · When using nuts, do not make the heat sink hole diameters larger than the diameter of the head of the screws used. A hole diameter about 15% larger than the diameter of the screw is desirable.
- · When tap screws are used, be sure that the diameter of the holes in the heat sink are not too small. A diameter about 15% smaller than the diameter of the screw is desirable.
- g. There is a method to mount the semiconductor device to the heat sink by using a spring band. But this method is not recommended because of possible displacement due to fluctuation of the spring force with time or vibration.

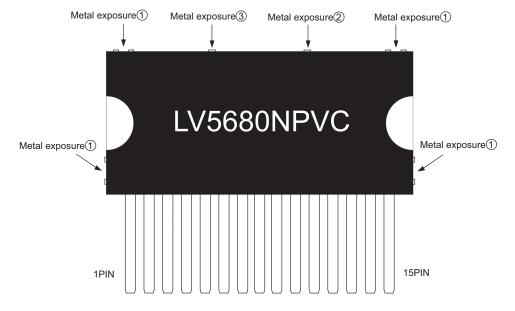
### Caution for implementing LV5680P to a system board

The package of LV5680P is HZIP15J which has some metal exposures other than connection pins and heatsink as shown in the diagram below. The electrical potentials of (2) and (3) are the same as those of pin 15 and pin 1, respectively. (2) (=pin 15) is the  $V_{CC}$  pin and (3) (=pin 1) is the ILM (regulator) output pin. When you implement the IC to the set board, make sure that the bolts and the heatsink are out of touch from (2) and (3). If the metal exposures touch the bolts which has the same electrical potential with GND, GND short occurs in ILM output and  $V_{CC}$ . The exposures of (1) are connected to heatsink which has the same electrical potential with substrate of the IC chip (GND). Therefore, (1) and GND electrical potential of the set board can connect each other.

#### • HZIP15J outline



• Frame diagram (LV5680NPVC) \*In the system power supply other than LV5680NPVC, pin assignment may differ.



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